

# GF1A - GF1M

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## General Purpose Rectifiers (Glass Passivated)

### Features

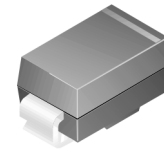
- Low Forward Voltage Drop
- High Current Capability
- Easy Pick and Place
- High Surge Current Capability
- This Device is Pb-Free and is RoHS Compliant



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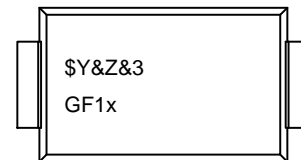
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**SMA  
CASE 403AE**  
(COLOR BAND DENOTES CATHODE)

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### MARKING DIAGRAM



\$Y	= ON Semiconductor Logo
&Z	= Assembly Plant Code
&3	= Data Code (Year & Week)
GF1x	= Specific Device Code
x	= A/B/D/G/J/K/M

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### ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

# GF1A – GF1M

## ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value							Units
		1A	1B	1D	1G	1J	1K	1M	
$V_{RRM}$	Maximum Repetitive Reverse Voltage	50	100	200	400	600	800	1000	V
$I_{F(AV)}$	Average Rectified Forward Current, @ $T_L = 125^\circ\text{C}$	1.0							A
$I_{FSM}$	Non-repetitive Peak Forward Surge Current 8.3 ms Single Half-Sine-Wave	30							A
$T_{stg}$	Storage Temperature Range	-65 to +175							$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-65 to +175							$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Units
$P_D$	Power Dissipation	1.8	W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient*	80	$^\circ\text{C}/\text{W}$
$R_{\theta JL}$	Thermal Resistance, Junction-to-Lead*	26	$^\circ\text{C}/\text{W}$

\*Device mounted on PCB with 0.2 x 0.2" (5.0 x 5.0 mm) copper pad areas.

## ELECTRICAL CHARACTERISTICS $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Device							Units
		1A	1B	1D	1G	1J	1K	1M	
$V_F$	Maximum Forward Voltage @ 1.0 A	1.0				1.2			V
$t_{rr}$	Maximum Reverse Recovery Time $I_F = 0.5\text{ A}$ , $I_R = 1.0\text{ A}$ , $I_{rr} = 0.25\text{ A}$	2.0							$\mu\text{s}$
$I_R$	Maximum Reverse Current @ Rated $V_R$ $T_A = 25^\circ\text{C}$ $T_A = 125^\circ\text{C}$	5.0				50			$\mu\text{A}$
$C_T$	Typical Capacitance $V_R = 4.0\text{ V}$ , $f = 1.0\text{ MHz}$	15							pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## PACKAGE MARKING AND ORDERING INFORMATION

Device	Device Marking	Package	Quantity†
GF1A	GF1A	SMA	7500 / Tape & Reel
GF1B	GF1B		
GF1D	GF1D		
GF1G	GF1G		
GF1J	GF1J		
GF1K	GF1K		
GF1M	GF1M		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# GF1A – GF1M

## TYPICAL CHARACTERISTICS

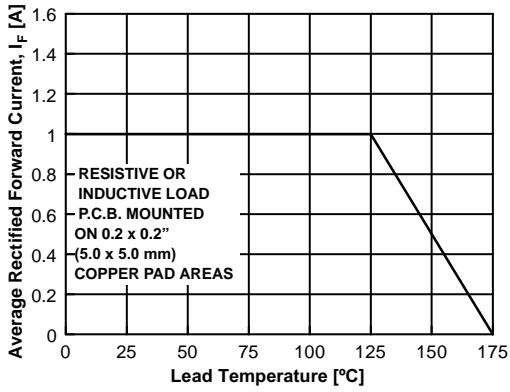


Figure 1. Forward Current Derating Curve

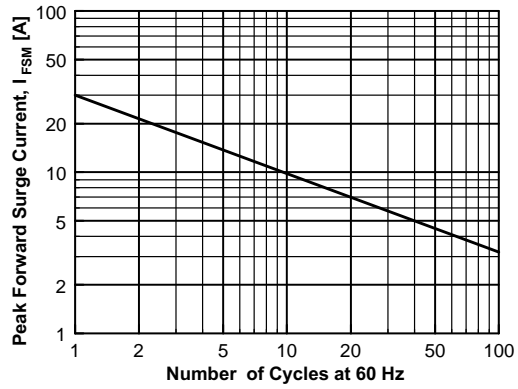


Figure 2. Non-Repetitive Surge Current

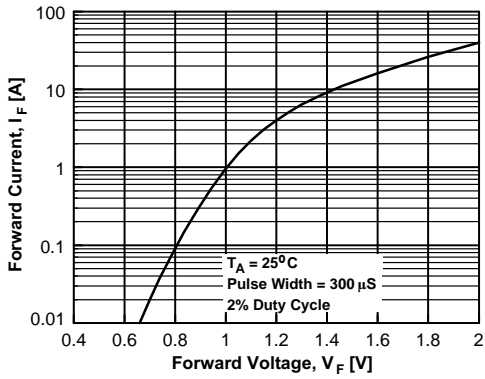


Figure 3. Forward Voltage Characteristics

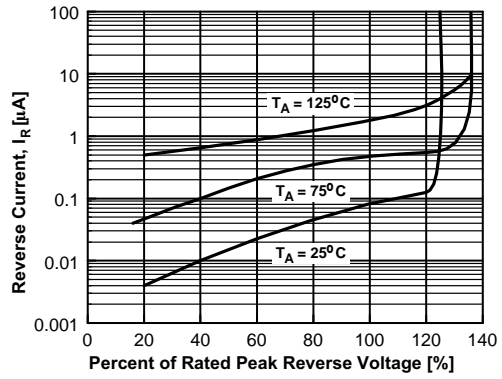


Figure 4. Reverse Current vs. Reverse Voltage

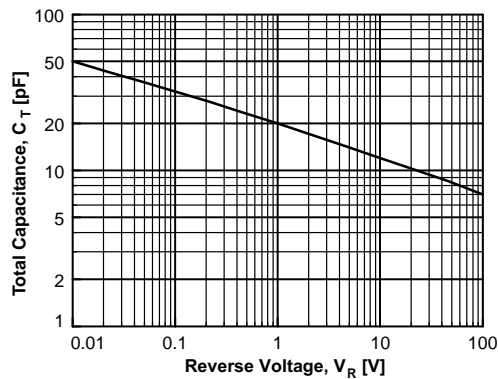


Figure 5. Total Capacitance

# MECHANICAL CASE OUTLINE

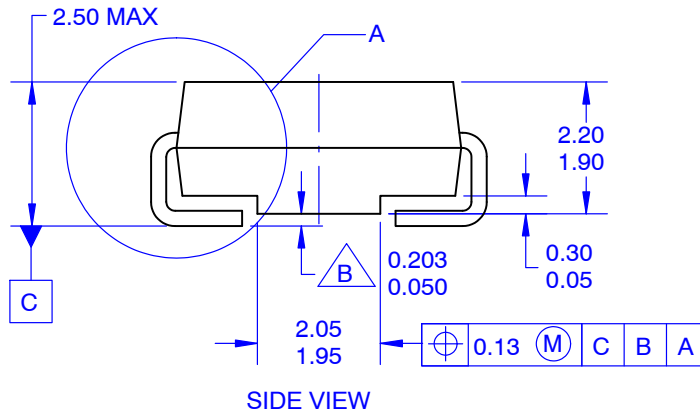
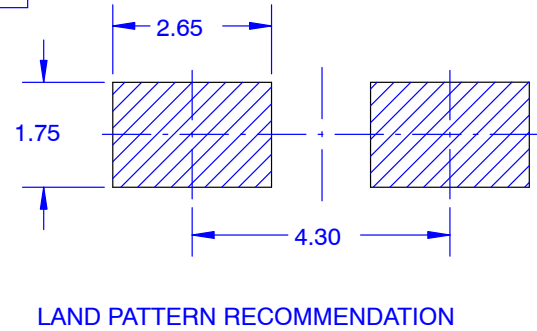
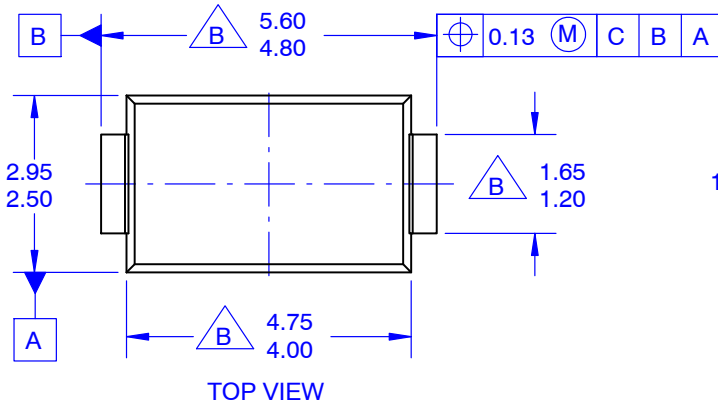
## PACKAGE DIMENSIONS

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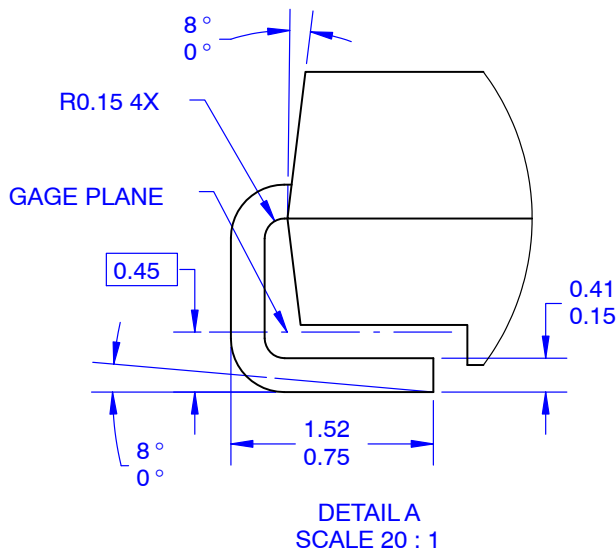
SMA  
CASE 403AE  
ISSUE O

DATE 31 AUG 2016



### NOTES:

- A. EXCEPT WHERE NOTED, CONFORMS TO JEDEC DO214 VARIATION AC.
- B. DOES NOT COMPLY JEDEC STANDARD VALUE.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- E. DIMENSIONS AND TOLERANCE AS PER ASME Y14.5-2009.
- E. LAND PATTERN STD. DIOM5025X231M



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